PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	EMBEDDED PROCESSING/26/16043
1.3 Title of PCI	ASE KaoHsiung (TAIWAN) - Tray Packing Material Change from Bubble Sheet to Foam End Cap - on listed products
1.4 Product Category	STM32x and STM8x
1.5 Issue date	2026-01-28

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	ASE Kaohsiung (Taiwan)

4. Description of change

	Old	**New**
4.1 Description	Old ASE tray packing method : - using bubble sheet, which is not compliant to ST requirement 0056593. - Old Inner box Dimension: 360x182x95 mm	New ASE tray packing method : - Foam sheet and foam end cap, are compliant to ST requirement 0056593. - New Inner box Dimension: 380x180x120 mm
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on Commercial Products. Inner cardboard box Dimension is changing.	

5. Reason / motivation for change

5.1 Motivation	To comply to ST requirement 0056593 tray packing with foam end cap.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools

7. Timing / schedule

7.1 Date of qualification results	2025-12-17
7.2 Intended start of delivery	2026-01-31
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	16043 Qualification Document.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-01-28

9. Attachments (additional documentations)

16043 Public product.pdf
16043 Qualification Document.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F030C6T6	
	STM32F030C8T6	
	STM32F030CCT6	
	STM32F030K6T6	
	STM32F030R8T6	
	STM32F031C4T6	
	STM32F051R8T6	
	STM32F070RBT6	
	STM32F072C8T6	
	STM32F072CBT6	
	STM32F072RBT6	
	STM32F072VBT6	
	STM32F091RCT6	
	STM32F100C8T6B	
	STM32F101C8T6	
	STM32F101CBT6	
	STM32F101RCT6	
	STM32F101RET6	
	STM32F101VCT6	
	STM32F103C8T6	
	STM32F103CBT6	
	STM32F103RCT6	
	STM32F103RET6	
	STM32F103VCT6	
	STM32F103VET6	
	STM32F103ZCT6	
	STM32F103ZET6	
	STM32F105VCT6	
	STM32F205RCT6	
	STM32F205RGT6	
	STM32F205VCT6	
	STM32F205VGT6	
	STM32F205ZET6	
	STM32F207VGT6	
	STM32F407IGH6	
	STM32F407VGT6	
	STM32F407VGT7	
	STM32F415RGT6	
	STM32F427VIT6	
	STM32F437IIT6	
	STM32F439ZGT6	
	STM32F446RCT6	
	STM32F446RCT7	
	STM32F446RET7	

	STM32F446VET6	
	STM32F746NGH6	
	STM32F767ZIT6	
	STM32F769NIH6	
	STM32F777IIT6	
	STM32F777IIT7	
	STM32G030K8T6	
	STM32G070KBT6	
	STM32G070RBT6	
	STM32G071RBT6	
	STM32G0B1CBU6	
	STM32G431C8U6	
	STM32G431CBU6	
	STM32H730VBT6	
	STM32H743VIT6	
	STM32H745XIH3	
	STM32H750IBK6	
	STM32H750VBT6	
	STM32L071RZT6	
	STM32L100R8T6	
	STM32L100RBT6	
	STM32L151R8T6	
	STM32L412KBU6	
	STM32MP157FAA1	
	STM32U599NIH6Q	
	STM32WLE5JBI6	
	STM8L151C6T6	

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